## **Product / Process Change Notification**

### N° 2013-065-A



Dear Customer,

Please find attached our INFINEON Technologies PCN:

### Infineon goes Green: Implementation of a Green version (RoHS and WEEE compliant) for Infineon Profet<sup>™</sup> products

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before 28. April 2014.
- Infineon aligns with the widely-recognized JEDEC STANDARD "JESD46", which stipulates: "Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Disclaimer:

If we do not receive any response by the date in the PCN above we consider this as the acceptance of the PCN. After the last order date as stated herein, purchase orders related to the unchanged product(s) cannot be accepted.

In case the customer rejects this PCN this PCN shall be considered a product discontinuation notice (PD).

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| SUBJECT OF CHANGE: | Implementation of a Green version (RoHS and WEEE compliant<br>Infineon Profet™ products. Transfer of PROFET <sup>™</sup> products from<br>conventional to LPL assembly line |  |
|--------------------|---|--|
| PRODUCTS AFFECTED: | See 1_cip13065  |  |
| REASON OF CHANGE:  | The products are converted to a green, RoHS, and WEEE compliant   |  |

The products are converted to a green, RoHS, and WEEE compliant version in order to meet market requirements. In order to secure supply Infineon needs to transfer to a new assembly line (called LPL assembly line).

| DESCRIPTION OF CHANGE: | <u>OLD</u>   | <u>NEW</u>   |
|------------------------|--|--|
| Package name           | P-TO220-7-128 (SMD)<br>P-TO220-5-62 (SMD)                | PG-TO263-7-2 (SMD)<br>PG-TO263-5-2 (SMD)                 |
| Package dimensions     | see customer information package                         | 3_cip13065   |
| plating at outer leads | PbSn   | Sn   |
| moisture level         | MSL1 @220°C  | MSL 3 @245°C   |
| ■ Data Sheet           | old package name<br>old package drawing<br>old SP number | new package name<br>new package drawing<br>new SP number |

#### **PRODUCT IDENTIFICATION:**

- On Packing level:
  - o Package name
  - o SP number
- On datasheet level:
  - o Package drawing
  - Package name
- SP number

available

available

#### TIME SCHEDULE:

- Final qualification report:
- First samples available:
- Start of delivery:
- Last order date of unchanged product:
- Last delivery date of unchanged product:

15-July-2014 or earlier on request 15-July-2014

31-December-2014

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| ASSESSMENT:<br>REMARK: | <ul> <li>Products are compatible to lead-free and lead-containing board assembly processes.</li> <li>Positive results from: visual inspection, solderability test, tin thickness, lead content check, whisker assessment</li> <li>Continuously SPC monitoring of solderability and tin thickness</li> <li>No impact on parameters and reliability proven via technology and product qualification. Processes are optimized to meet product performance according to specification.</li> <li>Please take care of the product discontinuation PD_017_14</li> </ul> |   |
|------------------------|--|---|
| DOCUMENTATION:         | 1_cip13065<br>3_cip13065<br>4_cip13065   | Product list<br>Customer information package<br>Data sheets |